

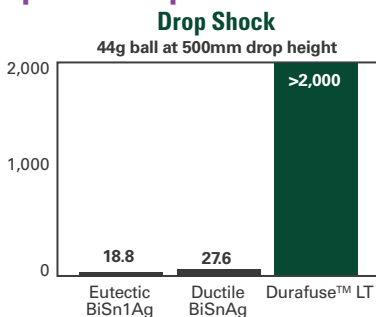
High-Reliability Alloy

Durafuse™ LT*

Innovative Low-Temperature Alloy Technology

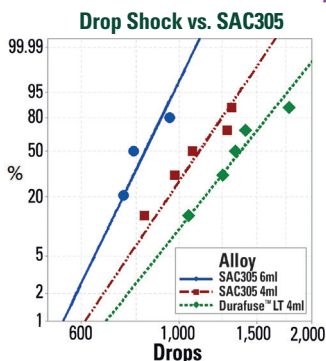
Durafuse™ LT is a novel mixed alloy system that solves the challenges of brittle bismuth-based, low-temperature solder joints. It provides drop shock resistance two orders of magnitude better than conventional Bi-based alloys and can produce equal or better drop shock performance when compared to SAC305.

Improves Drop Shock Resistance



- Improves drop shock resistance >2 orders of magnitude better compared to Bi-based

High-Performance Reliability



- Drop shock resilience
 - Outclasses BiSn or BiSnAg alloys
 - Performance equal to or better than SAC305
- Peak reflow below 210°C
- High re-melt temperature

Weibull plot of 100g ball with 500mm drop height.

*Patent Pending

Contact our engineers: askus@indium.com

Learn more: www.indium.com/durafuse

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified.

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High-Reliability Alloy

Durafuse™ LT

Innovative Low-Temperature Alloy Technology

WHY LOW-TEMP?



Reduces
Component Damage



Reduces
Warpage



Enables
Step Soldering



DROP SHOCK RELIABILITY



Brittle
Bi Alloy



Traditional
Low-Temp Solder Paste



PROVEN SOLUTION

Durafuse™ LT

The tough choice that's easy to make



The Ultimate Drop Shock
Solution to Low-Temp Soldering



About 20% of phones
manufactured in 2021
used Durafuse™ LT

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